

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	09712749			
<b>Filing Date:</b>	14-Nov-2000			
<b>Title of Invention:</b>	LOW PROFILE INTEGRATED MODULE INTERCONNECTS AND METHOD OF FABRICATION			
<b>First Named Inventor/Applicant Name:</b>	Chia-Yu Fu			
<b>Filer:</b>	David George Dolezal/Dee Matocha			
<b>Attorney Docket Number:</b>	CT00-020			
Filed as Large Entity				
<b>Utility under 35 USC 111(a) Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1510	1510
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1510